

Description

The AON7544-HXY uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

 $V_{DS} = 30V I_{D} = 100A$

 $R_{DS(ON)} < 5.5 \,\text{m}\Omega$ @ $V_{GS}=10V$

Application

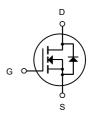
Battery protection

Load switch

Uninterruptible power supply



DFN3X3-8L DFN-8(3x3)



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AON7544-HXY	DFN3X3-8L/DFN-8(3x3)	100N03 XXX YYYY	5000

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V _D s	Drain-Source Voltage 30		V
V _G s	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	100	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	70	Α
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	25	Α
Ідм	Pulsed Drain Current ²	192	Α
EAS	Single Pulse Avalanche Energy ³	144.7	mJ
las	Avalanche Current	53.8	Α
P _D @T _C =25°C	Total Power Dissipation ⁴	62.5	W
P _D @T _A =25°C	Total Power Dissipation ⁴	4.5	W
Тэтс	Storage Temperature Range	-55 to 150	°C
Tu	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-ambient ¹	62	°C/W
Rejc	Thermal Resistance Junction-Case ¹	2.4	°C/W



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
∆BVbss/∆Tj	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.0213		V/°C
		V _{GS} =10V , I _D =30A		4	5.5	
RDS(ON)	Static Drain-Source On- Resistance ²	V _{GS} =4.5V , I _D =15A		5.2	6	mΩ
V _G S(th)	Gate Threshold Voltage		1.0		2.5	V
$\triangle V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-5.8		mV/°C
Ipss	Drain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =25°C			1	uA
1055	Dialii-Source Leakage Guiterit	V_{DS} =24V , V_{GS} =0V , T_J =55 $^{\circ}$ C			5	uA
Igss	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		26.5		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.4		Ω
Q_g	Total Gate Charge (4.5V)			31.6		
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =15A		8.6		nC
Qgd	Gate-Drain Charge	11D-13A		11.7		
Td(on)	Turn-On Delay Time			9		
Tr	Rise Time	V _{DD} =15V , V _{GS} =10V ,		19		
Td(off)	Turn-Off Delay Time	R _G =3.3Ω		58		ns
T _f	Fall Time	_I _D =15A		15.2		
Ciss	Input Capacitance			3075		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V ,		400		pF
Crss	Reverse Transfer Capacitance	_f=1MHz		315		
ls	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force			100	Α
Іѕм	Pulsed Source Current ^{2,6}	Current			192	Α
Vsp	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1	V

Diode Characteristics

Note

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- 3 .The EAS data shows Max. rating . The test condition is $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, L\text{=}0.1\text{mH}, I_{\text{AS}}\text{=}34\text{A}$
- 4. The power dissipation is limited by 150 °C junction temperature
- 5 .The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

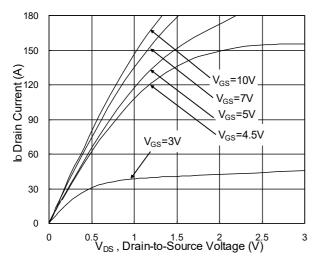


Fig.1 Typical Output Characteristics

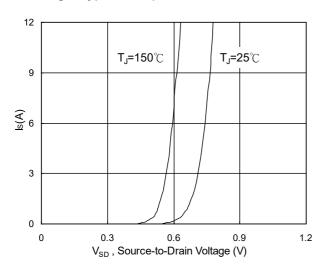


Fig.3 Forward Characteristics of Reverse

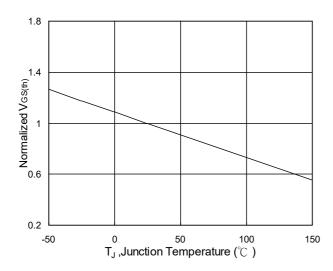


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

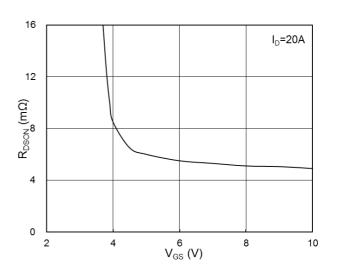


Fig.2 On-Resistance vs. G-S Voltage

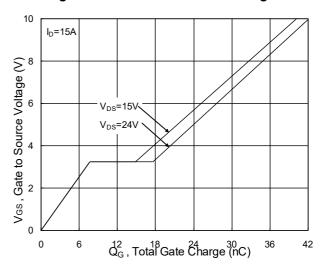


Fig.4 Gate-Charge Characteristics

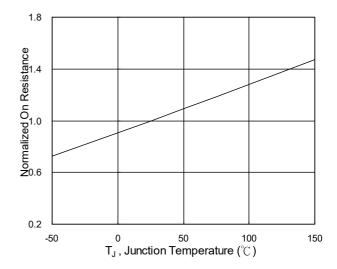
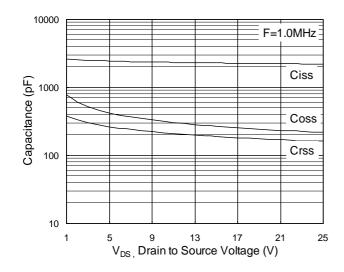


Fig.6 Normalized R_{DSON} vs. T_J





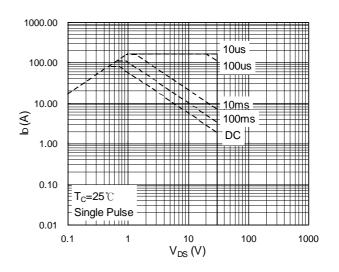


Fig.7 Capacitance

Fig.8 Safe Operating Area

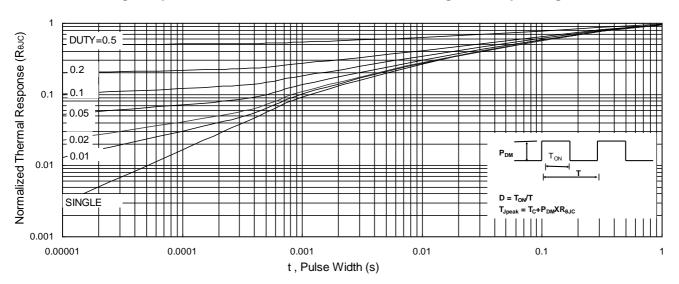


Fig.9 Normalized Maximum Transient Thermal Impedance

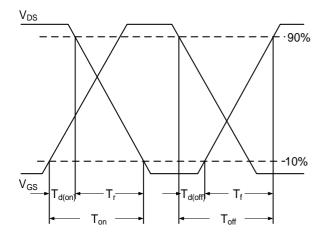


Fig.10 Switching Time Waveform

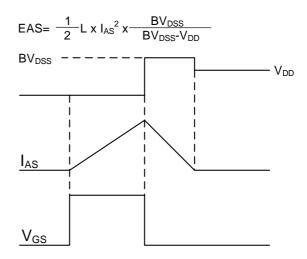
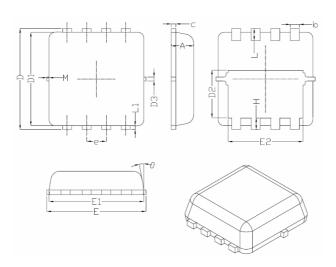


Fig.11 Unclamped Inductive Switching Waveform



DFN3X3-8L/DFN-8(3x3) Package Information



Symbol	Dimensions In Millimeters			
	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
M	*	*	0.15	
θ		10°	12 [°]	

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